

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
MUDUBAGILU UDAYA KUMAR	02/24/2016
PARESH BHAGVANBHAI RASADIYA	02/28/2016
BHARATKUMAR RAVJIBHAI PAGHADAR	02/24/2016
SAMBHAJI NANASAHEB CHOUGULE	02/24/2016
RECEIVING PARTY DATA	
Name:	SAUDI BASIC INDUSTRIES CORPORATION
Street Address:	P.O. BOX 5101
City:	RIYADH
State/Country:	SAUDI ARABIA
Postal Code:	11422
Name:	SABIC GLOBAL TECHNOLOGIES B.V.
Street Address:	PLASTICSLAAN 1
City:	BERGEN OP ZOOM
State/Country:	NETHERLANDS
Postal Code:	4612 PX
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14911562
CORRESPONDENCE DATA	
Fax Number:	(860)286-0115
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	860-286-2929
Email:	nturover@cantorcolburn.com
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Address Line 2:	22ND FLOOR
Address Line 4:	HARTFORD, CONNECTICUT 06103
ATTORNEY DOCKET NUMBER:	13POLY0013-US-PCT

NAME OF SUBMITTER:	LEAH M. REIMER, REG. NO. 39,341
SIGNATURE:	/Leah M. Reimer/
DATE SIGNED:	03/08/2016
Total Attachments: 4 source=7KA0063#page1.tif source=7KA0063#page2.tif source=7KA0063#page3.tif source=7KA0063#page4.tif	

ASSIGNMENT

Title of Invention: PROCESS FOR THE PREPARATION OF 2,2'-BIS-INDENYL BIPHENYL LIGANDS AND THEIR METALLOCENE COMPLEXES

This Assignment is directed to:

[] the attached application (SABIC Docket Number _____), or

[X] United States Patent application number 14/911,562 filed on February 11, 2016, which claims priority to Patent application number PCT/EP2014/067665 filed on August 19, 2014, which claims priority to European Applications EP13181090.5 filed August 20, 2013, EP13181087.1 filed August 20, 2013, and EP13181089.7 filed August 20, 2013.

Whereas, each undersigned inventor has made certain inventions, improvements, and discoveries (herein referred to as the "INVENTION") disclosed in the above-identified patent application (herein referred to as the "APPLICATION");

Whereas, SAUDI BASIC INDUSTRIES CORPORATION, a corporation of Saudi Arabia having a place of business at P.O. Box 5101, 11422 Riyadh, Saudi Arabia and SABIC GLOBAL TECHNOLOGIES B.V., a corporation of The Netherlands having a place of business at Plasticslaan 1, 4612 PX Bergen op Zoom, The Netherlands (hereinafter jointly referred to as "ASSIGNEES") desires to acquire or has acquired, and each undersigned inventor acknowledges the obligation to assign to ASSIGNEES, and the parties desire to use this Assignment to memorialize the grant to ASSIGNEES of the entire worldwide right, title, and interest in and to the INVENTION including all embodiments thereof, and in and to any and all patent applications and patents directed thereto;

Now, therefore, for good and valuable consideration, the receipt and sufficiency thereof being hereby acknowledged, each undersigned inventor (herein referred to as "ASSIGNOR") hereby sells or has sold, assigns or has assigned, and otherwise transfers or has transferred to the ASSIGNEES, its successors, legal representatives, and assigns, the entire worldwide right, title, and interest in and to the INVENTION, the APPLICATION, and any and all other patent applications and patents for the INVENTION which may be applied for or granted therefor in any and all countries and jurisdictions, including all priority applications, nonprovisionals, divisions, continuations, continuations-in-part, reissues, reexaminations, renewals, extensions, counterparts, substitutes, and extensions thereof, and all rights of priority resulting from the filing of such applications and granting of such patents; and any and all claims and causes of action, with respect to any of the foregoing, whether accruing before, on and/or after the date hereof, including all rights to and claims for damages, restitution and injunctive and other legal and equitable relief for past, present and future infringement, dilution, misappropriation, violation, misuse, breach or default, with the right but no obligation to sue for such legal and equitable relief and to collect, or otherwise recover, any such damages. In addition, each undersigned inventor hereby authorizes and requests any official whose duty it is to issue patents, to issue any patent on the INVENTION or from the APPLICATION to said ASSIGNEES, its successors, legal representatives, and assigns, the entire worldwide right, title, and interest in and to the same to be held and enjoyed by ASSIGNEES, its successors, legal representatives, and assigns to the full end of the terms for which any and all such patents may be granted, as fully and entirely as would have been held and enjoyed by the undersigned had this Assignment not been made; and each undersigned inventor agrees on behalf of themselves, their successors and legal representatives, to execute any and all documents and instruments and perform all lawful acts reasonably related to recording this Assignment or perfecting title to the INVENTION, the APPLICATION, and all related patents and applications, in ASSIGNEES, its successors, legal representatives, and assigns, whenever requested by ASSIGNEES, its successors, legal representatives, and assigns.

Each undersigned inventor also hereby grants ASSIGNEES, its successors, legal representatives, and assigns, the right to insert in this Assignment any further identification of the APPLICATION (including, but not limited to, Application Number and filing date, and Attorney Docket Numbers), and further grants ASSIGNEES, its successors, legal representatives, and assigns the right to execute confirmatory assignments on their behalf.

Signature: M. Udaya
Name of Inventor: MUDUBAGILU UDAYA KUMAR

Date: 24/2/2016

First Witness: [Signature]

Date: 24/2/2016

Printed Name: PRASHANT SUKUMAR SHENGU

Second Witness: [Signature]

Date: 24/2/2016

Printed Name: RAJESH SHIVAPPA KOTI

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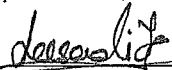
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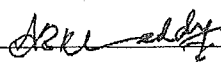
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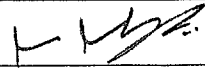
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Signature:  Date: 28/02/2016
Name of Inventor: PARESH BHAGVANBHAI RASADIYA

First Witness:  Date: 28/02/2016
Printed Name: Bhaskar Reddy Aluri

Second Witness:  Date: 28/02/2016
Printed Name: PRASANNA KUMAR PASHATLA

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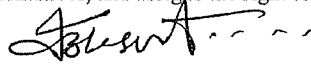
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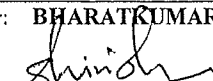
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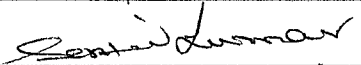
Signature: 
Name of Inventor: **BHARAT KUMAR RAVJIBHAI PAGHADAR**

Date: 24/02/2016

First Witness: 

Date: 24/02/2016

Printed Name: **SHRISH SHRIKANT ARHYANKAR**

Second Witness: 

Date: 24/02/2016

Printed Name: **Minor Santul Kumar**

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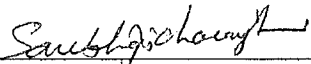
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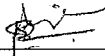
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 Name of Inventor: SAMBHAJI NANASAHEB CHOUGULE

First Witness:  Date: 24/02/2016
 Printed Name: PRASHANT SUKUMAR SHENGLE

Second Witness:  Date: 24/02/2016
 Printed Name: KENCHIAH LOHITH